

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings of claims in the application:

#### **Listing of Claims:**

Claims 1-33 (Canceled)

Claim 34 (Previously Presented): A semiconductor device comprising:

a BGA (ball grid array) type semiconductor device including a base plate and a plurality of bumps formed on a backside surface of the base plate; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have any bumps formed thereon,

said CSP type semiconductor device having a semiconductor element which has main and back surfaces, and side surfaces between the main and back surfaces, and a plurality of terminals which are formed on the main surface,

wherein the back surface and the entirety of the side surfaces of the semiconductor element are exposed.

Claim 35 (Previously Presented): The semiconductor device of claim 34, wherein the plurality of terminals of said CSP type semiconductor device are electrically connected

to the plurality of bumps via wiring patterns formed on the backside surface of the base plate.

Claim 36 (Previously Presented): The semiconductor device of claim 35, wherein the plurality of terminals of said CSP type semiconductor device are coupled to the wiring patterns via solder joints.

Claim 37 (Previously Presented): The semiconductor device of claim 34, wherein said CSP type semiconductor device is mounted on said BGA type semiconductor device so that a front surface of said CSP type semiconductor device faces the backside surface of the base plate.

Claim 38 (Previously Presented): The semiconductor device of claim 34, wherein the backside surface of the base plate is mounted to a printed circuit board via the plurality of bumps, and said CSP type semiconductor device as mounted on the backside surface of the base plate has a thickness less than a thickness of the plurality of bumps.

Claims 39-44 (Canceled)

Claim 45 (Previously Presented): The semiconductor device according to claim 34,

wherein said CSP type semiconductor device has a resin that covers the main surface of the semiconductor element and side surfaces of the terminals.

Claim 46 (Previously Presented): The semiconductor device according to claim 34, wherein the main surface of the semiconductor element faces the backside surface of the base plate.

Claim 47 (Previously Presented): The semiconductor device according to claim 45, wherein the main surface of the semiconductor element faces the backside surface of the base plate.

Claims 48-52 (Canceled):

Claim 53 (Currently Amended): ~~[[The]]~~ A semiconductor device of claim 34~~[[,]]~~  
comprising:

a BGA (ball grid array) type semiconductor device including a base plate and a plurality of bumps formed on a backside surface of the base plate; and

a CSP (chip size packaged) type semiconductor device mounted on an area of the backside surface of the base plate of said BGA type semiconductor device which does not have any bumps formed thereon,

said CSP type semiconductor device having a semiconductor element which has

main and back surfaces, and side surfaces between the main and back surfaces, and a plurality of terminals which are formed on the main surface,

wherein the back surface and the entirety of the side surfaces of the semiconductor element are exposed, and

wherein the main surface of the semiconductor element is sealed with a resin, and portions of each of the plurality of terminals are exposed from the resin.

Claim 54 (New): The semiconductor device according to claim 53, wherein said BGA type semiconductor device has a plurality of conductive portions on the backside surface of the base plate,

the semiconductor device further comprising a plurality of conductive members, each of which is located between a corresponding one of the plurality of conductive portions and the portion of a corresponding one of the plurality of terminals.

Claim 55 (New): The semiconductor device according to claim 54, wherein said conductive members are not sealed with said resin.

Claim 56 (New): The semiconductor device according to claim 54, wherein said conductive portions are solder.

Claim 57 (New): The semiconductor device according to claim 34, wherein said BGA

type semiconductor device has a semiconductor element, a size of the semiconductor element of said BGA type semiconductor device is smaller than a size of the semiconductor element of the said CSP type semiconductor device.

Claim 58 (New): The semiconductor device according to claim 34, wherein said BGA type semiconductor device and said CSP type semiconductor device are individually manufactured.